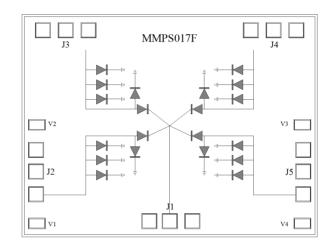


V1.0.0 PIN Diode MMIC SP4T Reflective Switch 10-40GHz

#### Features

- PIN Diode SP4T Reflective design
- Frequency:10-40GHz
- Isolation: 43dB Typical
- Insertion Loss: 2.0dB Typical
- Control Voltage:+5/-5V
- Switching Speed:10ns
- Die Size: 1.95 x 1.47 x 0.1 mm

#### **Functional Block Diagram**



### **Typical Applications**

- Voltage control
- Fast Switching Speed
- Low Insertion Loss and High Isolation
- Customization available upon request

#### **Electrical Specifications**

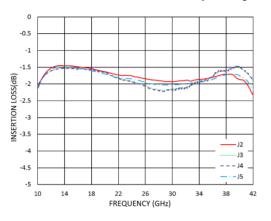
#### TA = +25°C, VCTL=+5/-5V , $\pm$ 10 mA Typical

Parameters	Min.	Тур.	Max.	Units
Frequency	10		40	GHz
Insertion Loss		2.0	2.5	dB
Isolation	35	43		dB
Input Return Loss (ON State)		10		dB
Output Return Loss (OFF State)		10		dB
P1dB - Output 1dB Compression		23		dBm
IIP3-Input Third Order Intercept		35		dBm
Switching Speed		10		ns

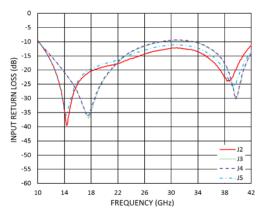


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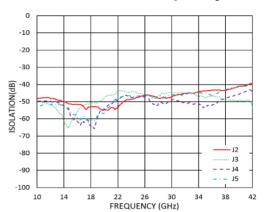
#### **Insertion Loss vs. Frequency**



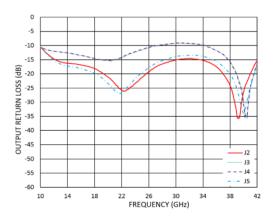
### Input Return Loss vs. Frequency



#### **Isolation vs. Frequency**



#### **Output Return Loss vs. Frequency**





V1.0.0 PIN Diode MMIC SP4T Reflective Switch 10-40GHz

### Absolute Maximum Ratings

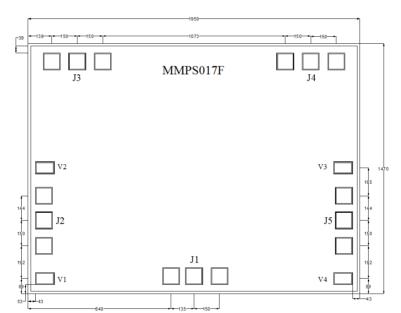
Max Incident C.W. RF Power	+31dBm	
DC Reverse Voltage	25V	
Bias Current	±50 mA	
Operating Temperature	-55°C to +85 °C	
Storage Temperature	-65°C to +150 °C	



ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS

# Outline Drawing:

All Dimensions in  $\boldsymbol{\mu}\boldsymbol{m}$ 



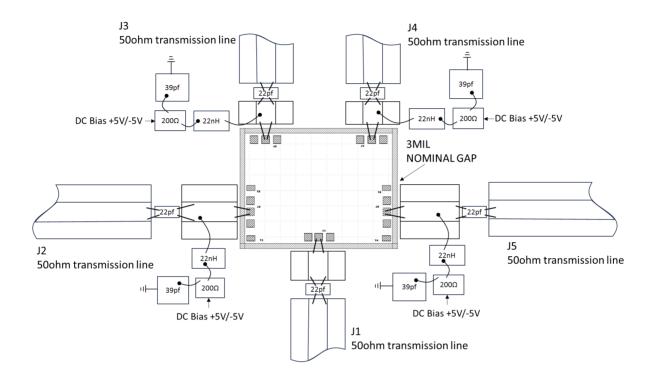
### True Table

Control Voltage			State				
J2	J3	J4	J5	J2→J1	J3→J1	J4→J1	J5→J1
-5V	+5V	+5V	+5V	ON	OFF	OFF	OFF
+5V	-5V	+5V	+5V	OFF	ON	OFF	OFF
+5V	+5V	-5V	+5V	OFF	OFF	ON	OFF
+5V	+5V	+5V	-5V	OFF	OFF	OFF	ON



0.0 PIN Diode MMIC SP4T Reflective Switch 10-40GHz

### Assembly Drawing



#### Notes:

- 1. Die thickness: 100µm
- 2. Typical bond pad is 100\*100µm<sup>2</sup>
- 3. Bond pad mentalization: Gold
- 4. Backside metallization: Gold
- 5. Backside of the die (GND)
- 6. No connection required for unlabeled bond pads

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